

ASMT-Mx00

Moonstone™ 1 W Power LED Light Source



Data Sheet



Lead (Pb) Free
RoHS 6 fully
compliant



Description

The Moonstone™ 1W Power LED Light Source is a high performance energy efficient device which can handle high thermal and high driving current. The exposed pad design has excellent heat transfer from the package to the motherboard.

The low profile package design is suitable for a wide variety of applications especially where height is a constraint.

The package is compatible with reflow soldering process. This will give more freedom and flexibility to the light source designer.

Applications

- Portable (flash light, bicycle head light)
- Reading light
- Architectural lighting
- Garden lighting
- Decorative lighting

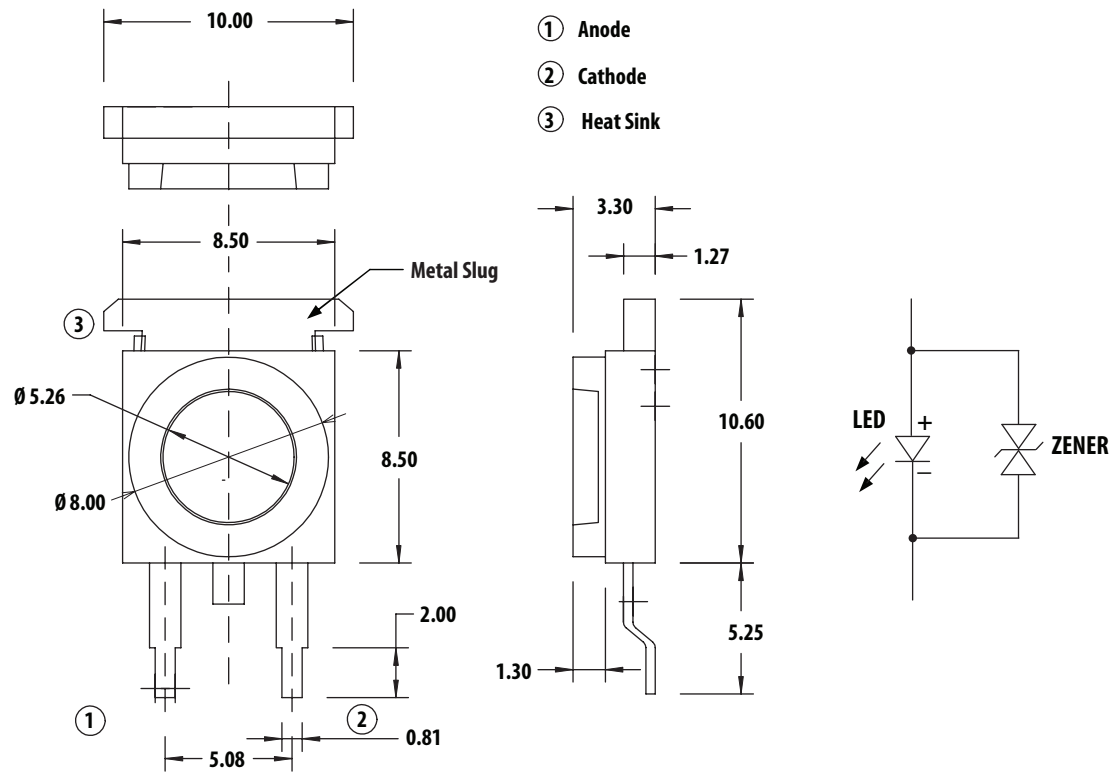
Features

- Available in Red, Amber, Green, and Blue color.
- Energy efficient
- Exposed pad for excellent heat transfer
- Suitable for reflow soldering process
- High current operation
- Long operation life
- Wide viewing angle
- Silicone encapsulation
- ESD Class HBM Class 3B (threshold > 8 kV)
- MSL 2A for InGaN products
- MSL 4 for AlInGaP products

Specifications

- AlInGaP technology for Red and Amber
- 2.1V (typ) at 350mA for AlInGaP
- InGaN technology for Green and Blue
- 3.2V (typ) at 350mA for InGaN

Package Dimensions



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm, unless otherwise specified.
3. Metal slug is connected to anode for electrically non-isolated option.

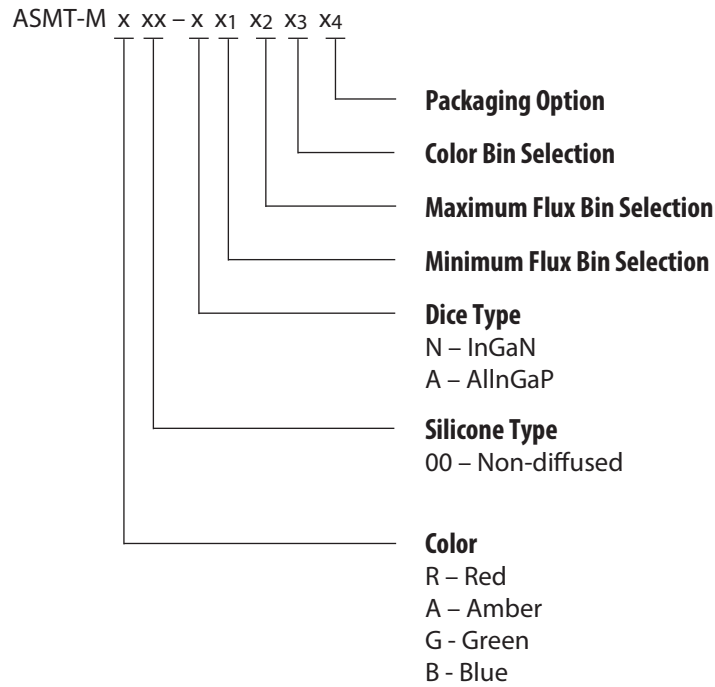
Device Selection Guide ($T_j = 25^\circ\text{C}$)

Part Number	Color	Luminous Flux, $\phi_v^{[1,2]}$ (lm)			Test Current (mA)	Dice Technology
		Min.	Typ.	Max.		
ASMT-MR00-AHJ00	Red	33.0	40.0	56.0	350	AlInGaP
ASMT-MA00-AGH00	Amber	25.5	35.0	43.0	350	AlInGaP
ASMT-MA00-AHJ00		33.0	40.0	56.0	350	AlInGaP
ASMT-MG00-NJK00	Green	43.0	60.0	73.0	350	InGaN
ASMT-MG00-NLM00		73.0	85.0	124.0	350	InGaN
ASMT-MB00-NDF00	Blue	11.5	15.0	25.5	350	InGaN

Notes

1. ϕ_v is the total luminous flux output as measured with an integrating sphere at 25 ms mono pulse condition.
2. Flux tolerance is $\pm 10\%$.

Part Numbering System



Note:

1. For selection details, see page 8.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$)

Parameter	AlInGaP	InGaN	Units
DC Forward Current ^[1]	350	350	mA
Peak Pulsing Current ^[2]	1000	1000	mA
Power Dissipation	805	1225	mW
LED Junction Temperature	125	110	°C
Operating Ambient Temperature Range at 350 mA	-40 to +115	-40 to +100	°C
Storage Temperature Range	-40 to +120	-40 to +120	°C
Soldering Temperature	See Figure 17		
Reverse Voltage ^[3]	Not recommended		

Notes:

1. DC forward current – derate linearly based on Figure 5 for AlInGaP and Figure 13 for InGaN.
2. Pulse condition duty factor = 10%, Frequency = 1 kHz.
3. Not recommended for reverse bias operation.

Optical Characteristics at 350 mA ($T_j = 25^\circ\text{C}$)

Part Number	Color	Peak Wavelength, λ_{PEAK} (nm)	Dominant Wave- length, $\lambda_d^{[1]}$ (nm)	Viewing Angle, $2\theta_{1/2}^{[2]}$ ($^\circ$)	Luminous Efficiency (lm/W)
		Typ.	Typ.	Typ.	Typ.
ASMT-MR00-AHJ00	Red	635	625	120	54
ASMT-MA00-AGH00	Amber	598	590	120	48
ASMT-MA00-AHJ00		598	590	120	54
ASMT-MG00-NJK00	Green	519	525	120	54
ASMT-MG00-NLM00		519	525	120	76
ASMT-MB00-NDF00	Blue	454	460	120	13

Electrical Characteristic at 350 mA ($T_j = 25^\circ\text{C}$)

Dice type	Forward Voltage V_f (V) at $I_f = 350$ mA			Thermal Resistance $R\theta_{j-ms}$ ($^\circ\text{C/W}$) ^[1]
	Min.	Typ.	Max.	Typ.
AllnGaP	1.7	2.1	2.3	10
InGaN	2.8	3.2	3.5	10

Note:

1. $R\theta_{j-ms}$ is Thermal Resistance from LED junction to metal slug.

AllnGaP

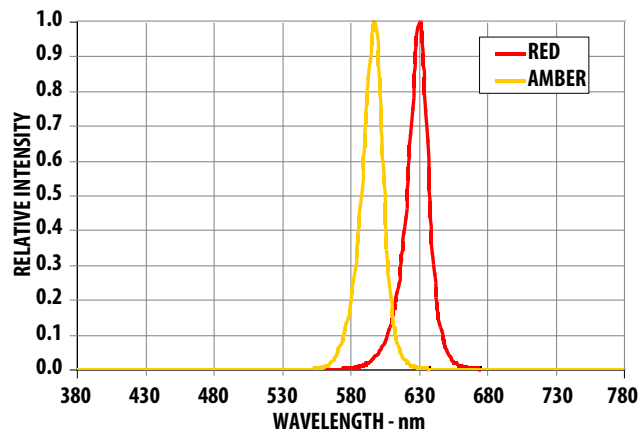


Figure 1. Relative Intensity vs. Wavelength for AllnGaP

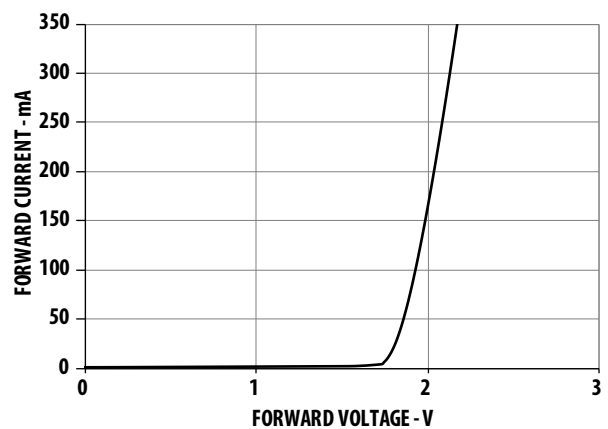


Figure 2. Forward Current vs. Forward Voltage for AllnGaP

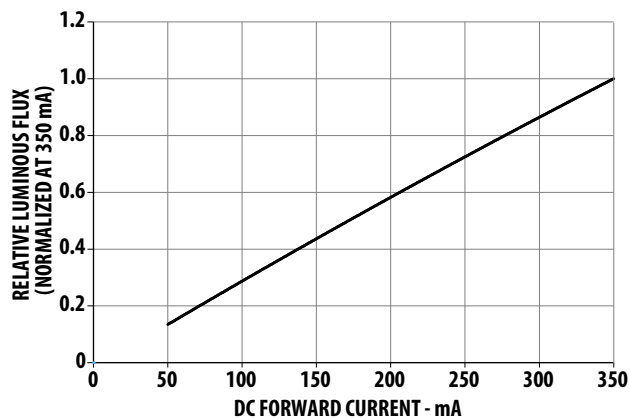


Figure 3. Relative Luminous Flux vs. Mono Pulse Current for AllnGaP

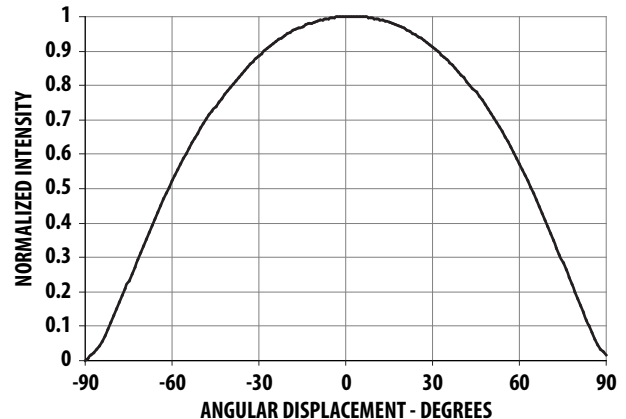


Figure 4. Radiation Pattern for AllnGaP

AllnGaP

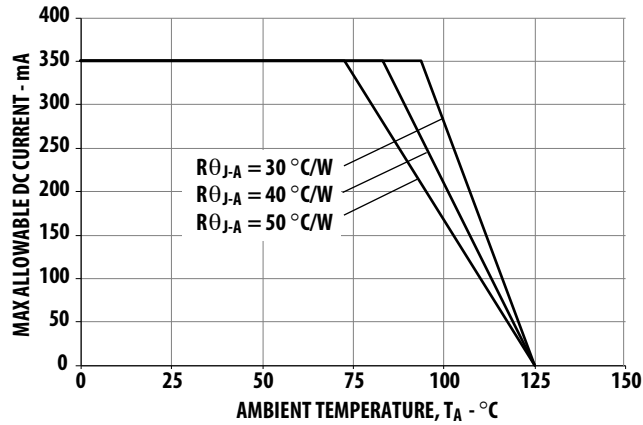


Figure 5. Maximum forward current vs. ambient temperature for AllnGaP
 Derated based on $T_{JMAX} = 125\text{ °C}$, $R_{\theta JA} = 30\text{ °C/W}$, 40 °C/W and 50 °C/W

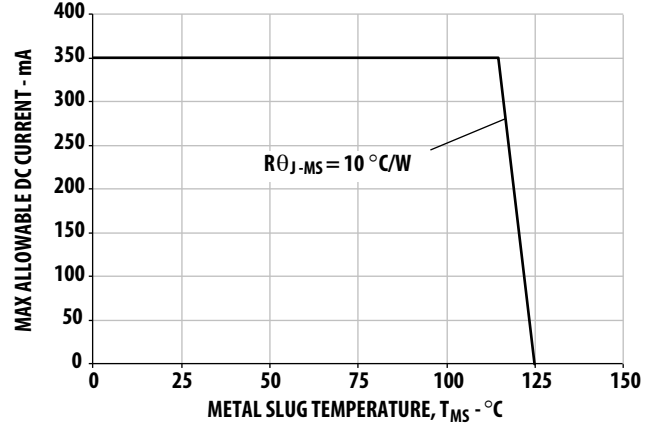


Figure 6. Maximum Forward Current vs. Metal Slug Temperature for AllnGaP
 Derated based on $T_{JMAX} = 125\text{ °C}$, $R_{\theta J-MS} = 10\text{ °C/W}$

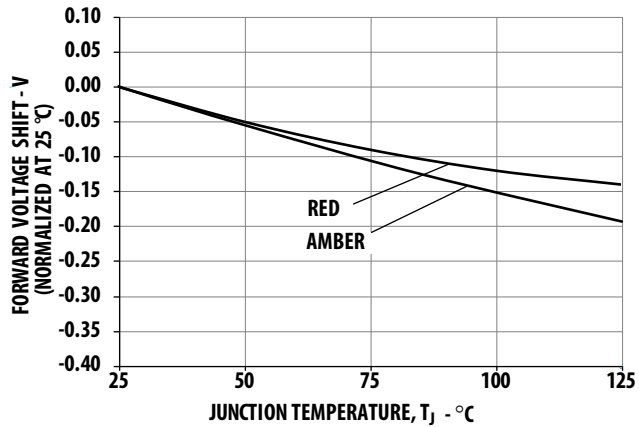


Figure 7. Forward voltage shift vs. junction temperature for AllnGaP

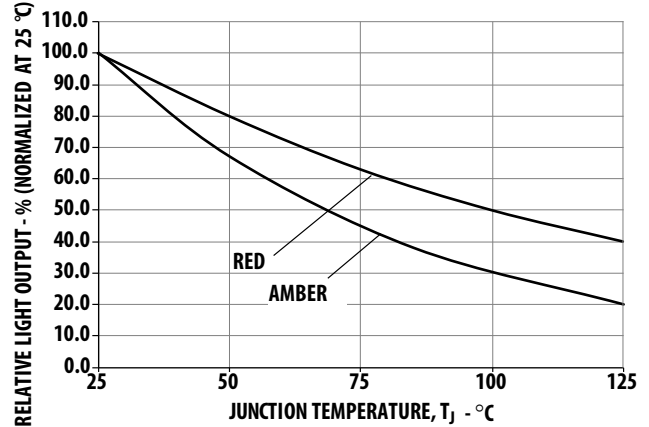


Figure 8. Relative Light Output vs. junction temperature for AllnGaP

InGaN

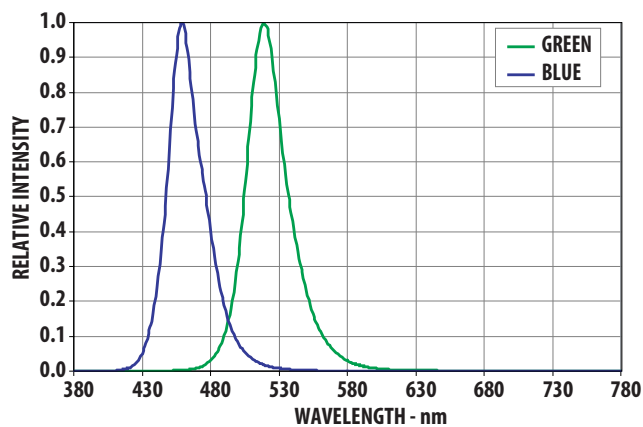


Figure 9. Relative Intensity vs. Wavelength for InGaN

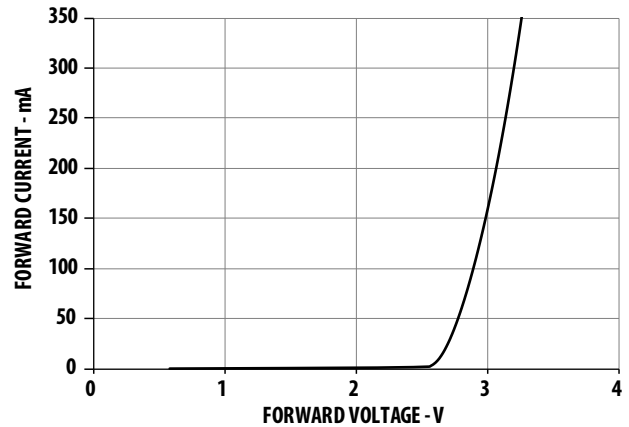


Figure 10. Forward Current vs. Forward Voltage for InGaN

InGaN

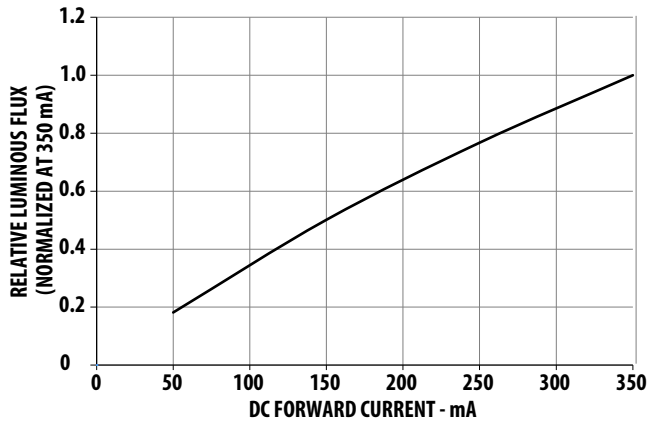


Figure 11. Relative Luminous Flux vs. Mono Pulse Current for InGaN

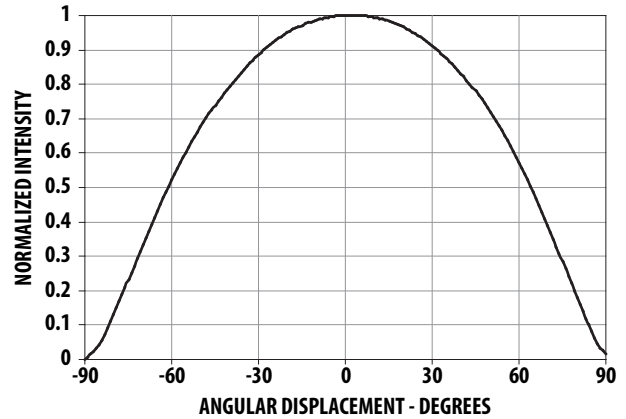


Figure 12. Radiation Pattern for InGaN

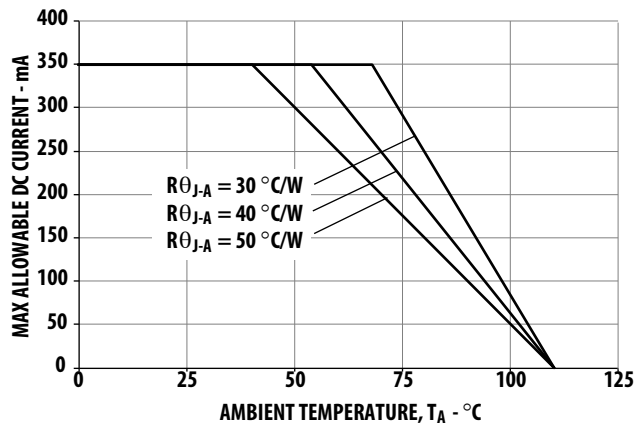


Figure 13. Maximum Forward Current vs. Ambient Temperature for InGaN Derated based on $T_{JMAX} = 110^{\circ}\text{C}$, $R_{\theta JA} = 30^{\circ}\text{C/W}$, 40°C/W and 50°C/W

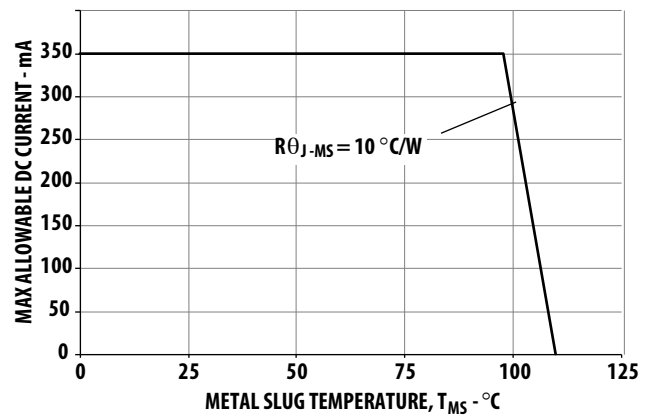


Figure 14. Maximum Forward Current vs. Metal Slug Temperature for InGaN Derated based on $T_{JMAX} = 110^{\circ}\text{C}$, $R_{\theta J-MS} = 10^{\circ}\text{C/W}$

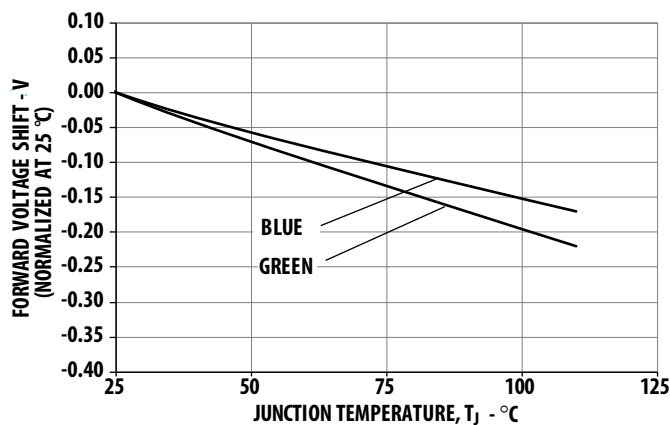


Figure 15. Forward voltage shift vs. junction temperature for InGaN

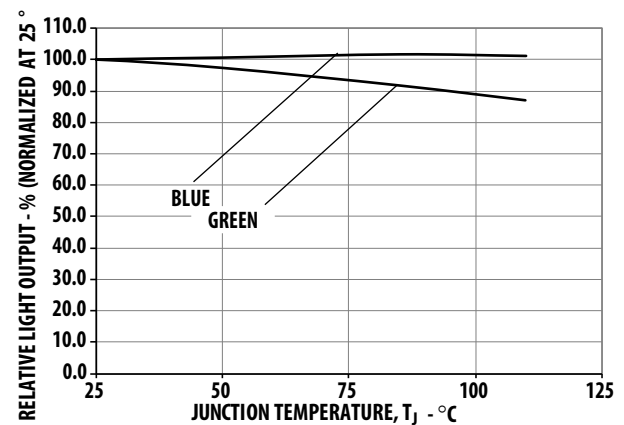
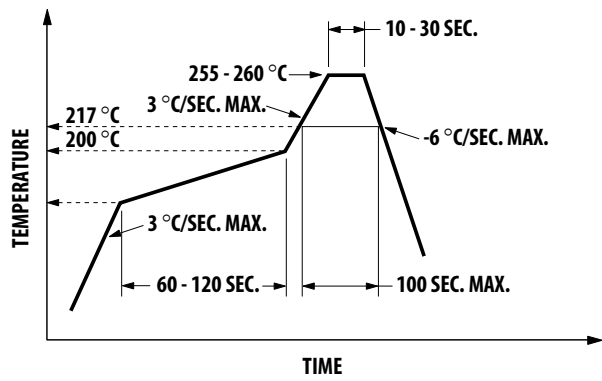


Figure 16. Relative Light Output vs. junction temperature for InGaN

Note:

For detailed information on reflow soldering of Avago surface mount LEDs, refer to Avago Application Note AN1060 *Surface Mounting SMT LED Indicator Components*.



(Acc. to J-STD-020C)

Figure 17. Recommended reflow soldering profile

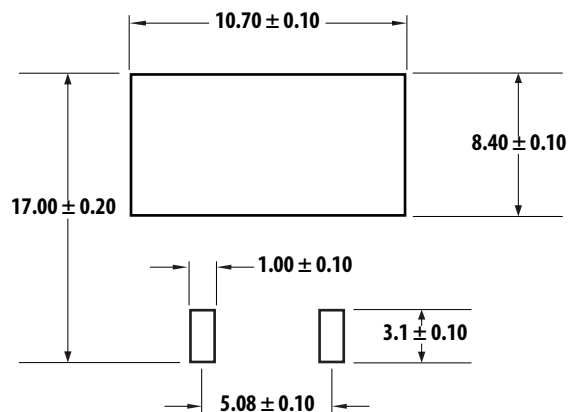


Figure 18. Recommended soldering land pattern

Option Selection Details

ASMT-Mxxx – x x₁ x₂ x₃ x₄

x₁ – Minimum Flux Bin Selection

x₂ – Maximum Flux Bin Selection

x₃ – Color Bin Selection

x₄ – Packaging Option

Color Bin Selection [x₃]

Individual reel will contain parts from one full bin only.

Other Colors

0	Full Distribution
Z	A and B
Y	B and C
W	C and D
V	D and E
Q	A, B and C
P	B, C and D
N	C, D and E

Flux Bin Limit [x₁ x₂]

Bin	Luminous Flux (lm) at I _F = 350mA	
	Min.	Max.
D	11.5	15.0
E	15.0	19.5
F	19.5	25.5
G	25.5	33.0
H	33.0	43.0
J	43.0	56.0
K	56.0	73.0
L	73.0	95.0
M	95.0	124.0

Tolerance for each bin limits is ±10%

Color Bin Limits

Color	Bin	Min.	Max.
Red	Full Distribution	620.0	635.0
Amber	A	582.0	584.5
	B	584.5	587.0
	C	587.0	589.5
	D	589.5	592.0
	E	592.0	594.5
Blue	A	455.0	460.0
	B	460.0	465.0
	C	465.0	470.0
	D	470.0	475.0
Green	A	515.0	520.0
	B	520.0	525.0
	C	525.0	530.0
	D	530.0	535.0

Tolerance: ± 1 nm

Packaging option [x₄]

Selection	Option
0	Tube
1	Tape & Reel

Example

ASMT-MR00-AHJ00

ASMT-MR00-Axxxx – AlInGaP Red, Non-diffused

- x₁ = H – Minimum Flux Bin H
- x₂ = J – Maximum Flux Bin J
- x₃ = 0 – Full Distribution
- x₄ = 0 – Tube Option

Packing Tube - Option 0

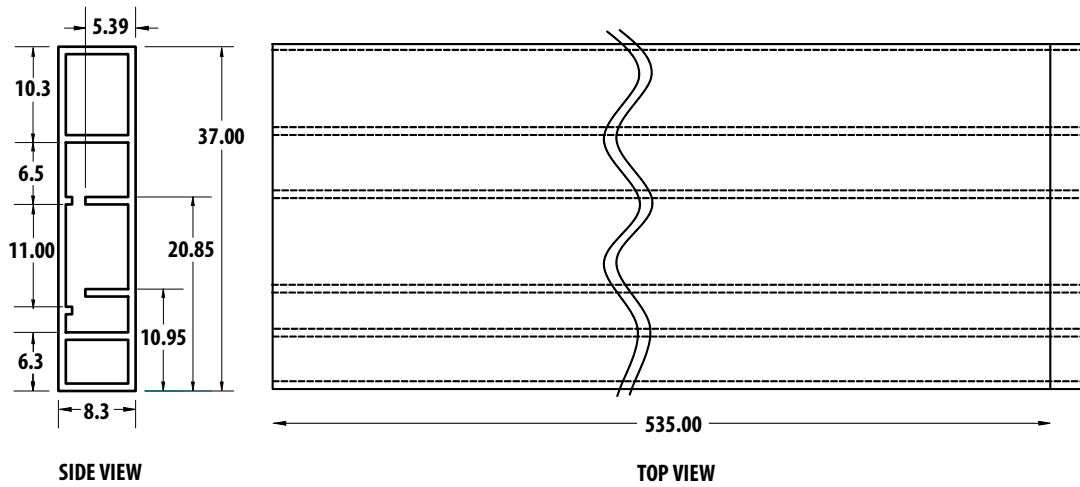


Figure 19. Tube dimensions

Tape & Reel - Option 1

Tape Dimension

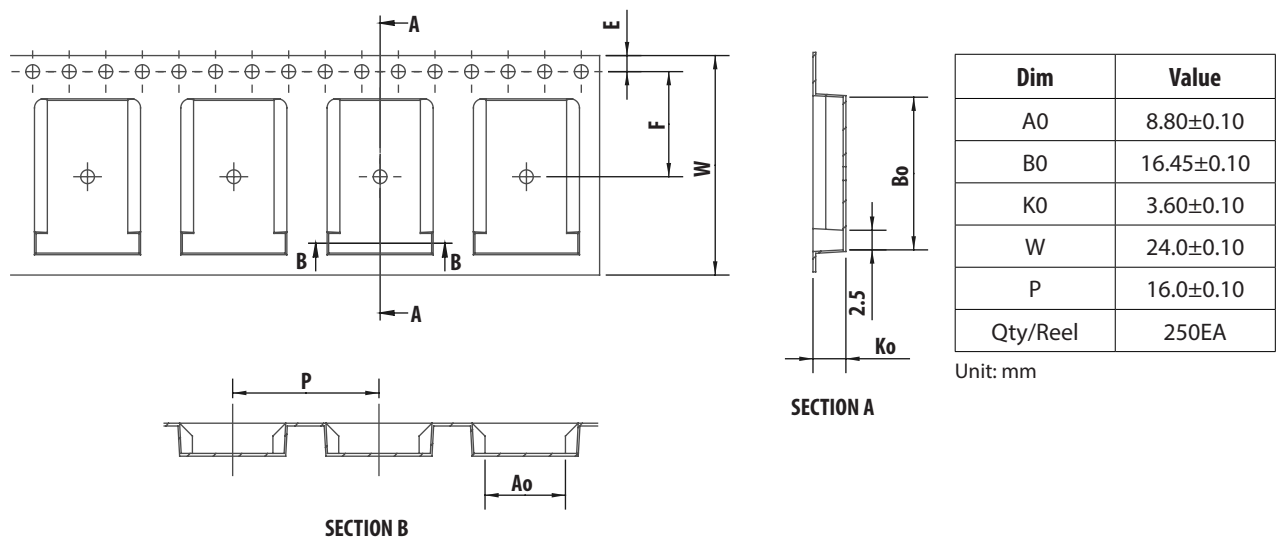


Figure 20. Carrier tape dimensions

Tape & Reel - Option 1 (Cont.)

Tape Dimension

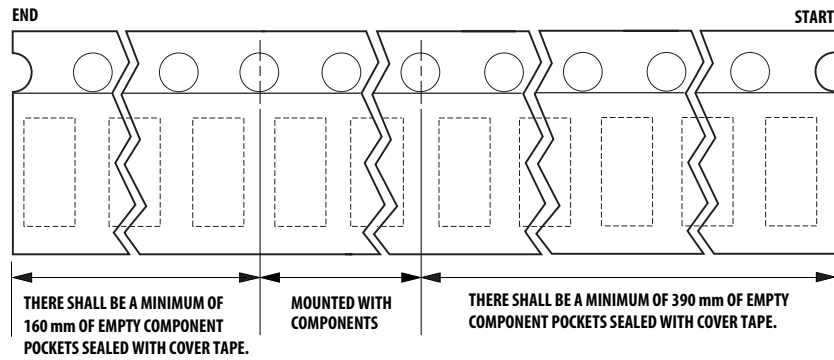


Figure 21. Carrier tape leader and trailer dimensions

Reel Dimensions

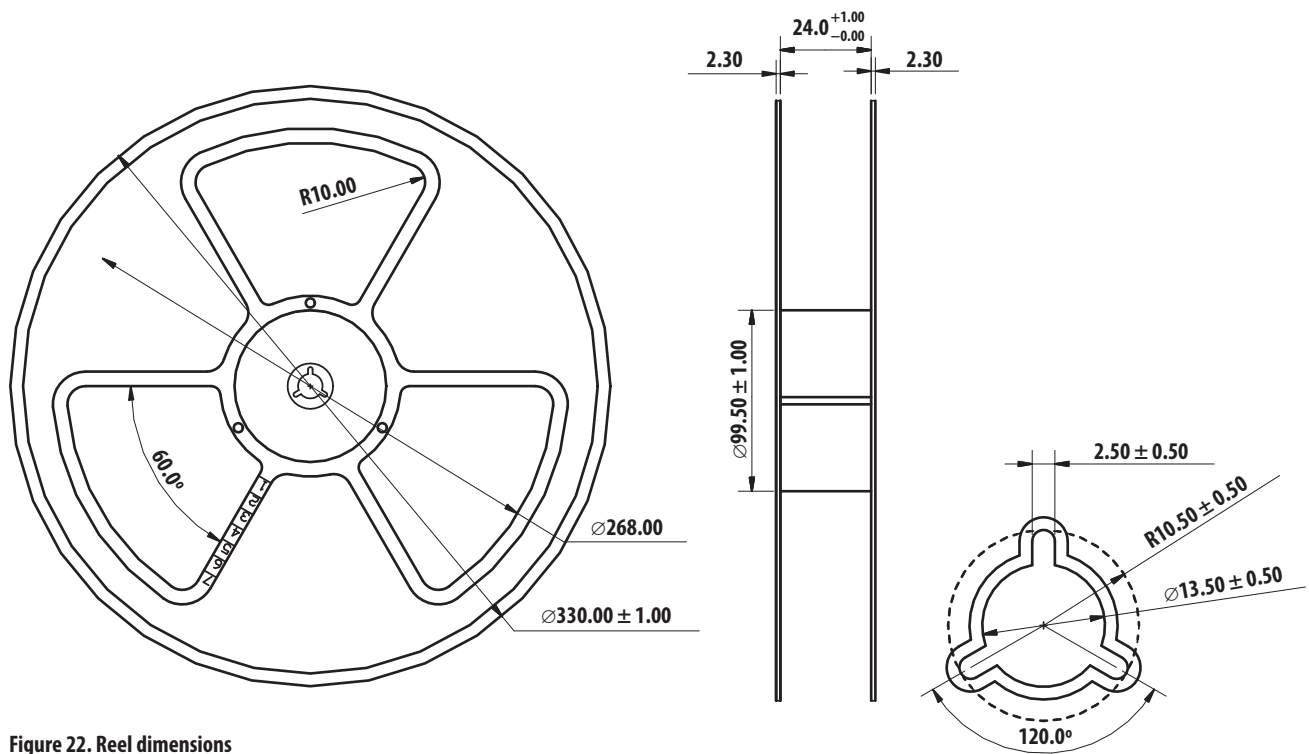


Figure 22. Reel dimensions

Handling Precaution

The encapsulation material of the product is made of silicone for better reliability of the product. As silicone is a soft material, please do not press on the silicone or poke a sharp object onto the silicone. These might damage the product and cause premature failure. During assembly or handling, the unit should be held on the body only. Please refer to Avago Application Note AN5288 for detail information.

Moisture Sensitivity

This product is qualified as Moisture Sensitive Level 2a for InGaN devices and MSL 4 for AlInGaP devices per Jedec J-STD-020. Precautions when handling this moisture sensitive product is important to ensure the reliability of the product. Do refer to Avago Application Note AN5305 Handling of Moisture Sensitive Surface Mount Devices for details.

A. Storage before use

- Unopen moisture barrier bag (MBB) can be stored at $< 40^{\circ}\text{C}/90\%\text{RH}$ for 12 months. If the actual shelf life has exceeded 12 months and the humidity indicator card (HIC) indicates that baking is not required, then it is safe to reflow the LEDs per the original MSL rating.
- It is not recommended to open the MBB prior to assembly (e.g., for IQC).

B. Control after opening the MBB

- The humidity indicator card (HIC) shall be read immediately upon opening of MBB.
- The LEDs must be kept at $<30^{\circ}\text{C}/60\%\text{RH}$ at all time and all high temperature related process including soldering, curing or rework need to be completed within 672 hours for MSL 2a and 72 hours for MSL 4.

C. Control for unfinished reel

- For any unused LEDs, they need to be stored in sealed MBB with desiccant or desiccator at $<5\%\text{RH}$.

D. Control of assembly boards

- If the PCB soldered with the LEDs is to be subjected to other high temperature processes, the PCB need to be stored in sealed MBB with desiccant or desiccator at $< 5\%\text{RH}$ to ensure no LEDs have exceeded their floor life of 672 hours for MSL 2a and 72 hours for MSL 4.

E. Baking is required if

- HIC "10%" indicator is not blue and "5%" indicator is pink. - The LEDs are exposed to condition of $>30^{\circ}\text{C}/60\%\text{RH}$ at any time.
- The LEDs floor life exceeded 672 hours for MSL 2a and 72 hours for MSL 4.

Recommended baking condition: $60 \pm 5^{\circ}\text{C}$ for 20 hrs.

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